PCN Number: 201512180		001			PCN Date:		12/18/2015	
Title: Datasheet fo	or TPS43340-Q1							
Customer Contact:	PCN Manager				ept:	Quality Services		
Change Type:								
Assembly Site			Design		Wafer	Bum	p Site	
Assembly Process		\boxtimes	Data Sheet		Wafer Bump Material			
Assembly Materials			Part number change			Wafer Bump Process		
Mechanical Specification			Test Site			Wafer Fab Site		
Packing/Shipping/Labeling			Test Process			Wafer Fab Materials		
					Wafer	· Fab I	Process	
		No	tification Details					
Description of Change								
Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(s) is updated as seen in the change revision history below:								
					•	ia Te	XAS	
TPS43340-Q1								
SLVSB16E – NOVEMBER 2011 – REVISED DECEMBER 2015 www.ti.com								
CHOOKE NOVEMBER OF THE PROPERTY OF THE PROPERT								
Changes from Revision D (July 2015) to Revision E						Page		
Update the HBM ESD ratings and added the MM ESD rating back in the ESD Ratings table						8		
								
Device Family			Change From: Cha		Chan	ge To:		
TPS43340-Q1	,		SLVSB16D			SLVSB16E		
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/product/tps43340-q1								
	•	•						
Reason for Change:								
To more accurately ref	lect device ch	narac	cteristics.					
Anticipated impact of	n Fit, Form,	, Fur	nction, Quality or Reliab	ilit	ty (posi	tive ,	/ negative):	
	This is a spec	cifica	ation change announceme	nt o	only. Th	ere ar	e no changes	
to the actual device.								
Changes to product	identificatio	n re	sulting from this PCN:					
None.								
Product Affected:								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com